

*cl*  
*cont.*  
sealed space formed between said hybrid integrated circuit substrate and said transparent substrate

*A2*  
--4. (Amended) A hybrid integrated circuit device according to claim 1, further comprising a gas for preventing said light emitting element and/or said electrodes from deteriorating, said gas filling the space defined by said substrate, said transparent substrate and said seal.--

--5. (Amended) A hybrid integrated circuit device according to claim 1, further comprising a spacer made of an insulating material which is disposed inside said seal between said hybrid integrated circuit substrate and said transparent substrate.--

*A3*  
--8. (Amended) A consolidated hybrid integrated circuit device according to claim 18 wherein said hybrid integrated circuit substrates are arranged in a matrix array and at least end ones of said hybrid integrated circuit substrates are inclined at a predetermined angle with respect to a centrally located hybrid integrated circuit substrate.--

--14. (Amended) A hybrid integrated circuit device according to claim 1, wherein the surface of the hybrid integrated circuit substrate is covered with solder resist.--

*Sub*  
*AX*  
--15. (Amended) A hybrid integrated circuit device according to claim 1, wherein the hybrid integrated circuit substrate is made of glass.--

--16. (Amended) A consolidated hybrid integrated circuit device according to claim 8, wherein the substrates are arranged in a matrix array and at least both end substrates is inclined in vertical and lateral directions so as to approximate a paraboloid, and an object to be heated is disposed in a focal point of the paraboloid.--

Please add claims 17 and 18:

*A5*  
-- 17. A hybrid integrated circuit device according to claim 1 wherein:  
said first electrode is formed on a region of said surface of the hybrid integrated circuit substrate and said first electrode is made of copper covered with an oxidation resistant metal;

said second electrode is formed on another region of said surface of the hybrid integrated circuit substrate and said second electrode is made of copper covered with an oxidation resistant metal;

a rear face of said light emitting element is electrically connected to said first electrode; and

further comprising an electrical connection between said second electrode and an electrode on a surface of said light emitting element.--

A5  
cont.  
--18. A consolidated hybrid integrated circuit device comprising a plurality of hybrid integrated circuit devices according to claim 1 wherein:

said first electrode is formed on a region of said surface of the hybrid integrated circuit substrate and said first electrode is made of copper covered with an oxidation resistant metal;

said second electrode is formed on another region of said surface of the hybrid integrated circuit substrate and said second electrode is made of copper covered with an oxidation resistant metal;

a rear face of said light emitting element is electrically connected to said first electrode; and

further comprising an electrical connection between said second electrode and an electrode on a surface of said light emitting element; and

electrical connections between said first electrodes and between said second electrodes.--

add C3  
REMARKS

This is Applicants' Response to the Office Action mailed September 13, 2001. That Action rejected claims 5, 8, 9 and 14 under 35 USC § 112, ¶ 2 as indefinite. Claims 1-16 were rejected under 35 USC § 103(a) as unpatentable over Nagane et al. in view of Liu.

Claims 1, 4-5, 8 and 14-16 have been amended, and claims 2 and 3 have been rewritten as claim 17 and 18, to more particularly point out and distinctly claim Applicants' inventions, as required by 35 USC § 112, ¶ 2. As stated in detail below, Applicants' contend that the cited prior art does not suggest or teach the subject matter of either Applicants' original or amended claims. Claims 1 and 4-18 remain under consideration.